

### 140V PNP LOW VCESAT TRANSISTOR IN PowerDI3333-8

#### **Features**

- BV<sub>CEO</sub> > -140V
- Small Form Factor Thermally Efficient Package.
   Enables Higher Density End Products
- I<sub>C</sub> = -4A Continuous Collector Current
- I<sub>CM</sub> = -10A Peak Pulse Current
- Low Saturation Voltage V<sub>CE(sat)</sub> < -120mV @ I<sub>C</sub> = -1A
- $R_{SAT}$  = 72m $\Omega$  for a Low Equivalent On-Resistance
- h<sub>FE</sub> Specified up to -10A for a High Gain Hold-Up
- Rated to +175°C Ideal For High Temperature Environment
- Wettable Flank For Improved Optical Inspection
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

### **Mechanical Data**

- Case: PowerDI<sup>®</sup>3333-8
- Case Material: Molded Plastic. "Green" Molding Compound.
   UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads Solderable per MIL-STD-202, Method 208 ©3
- Weight: 0.03 grams (Approximate)

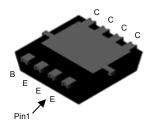
### **Applications**

- Motor Driving
- Line Switching
- High-Side Switches

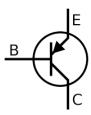
PowerDI3333-8 (SWP) (Type UX)







Bottom View



Device Symbol

### Ordering Information (Note 4)

Part Number	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
DXTP03140BFG-7	2K2	7	12	2000

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free
- and Lead-free.

  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/products/packages.html.

### **Marking Information**

PowerDI3333-8 (SWP) (Type UX)



2K2= Product Type Marking Code

YYWW = Date Code Marking

YY = Last Two Digits of Year (ex: 19 = 2019)

WW = Week Code (01 to 53)



# Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CBO</sub>	-180	V
Collector-Emitter Voltage	V <sub>CEO</sub>	-140	V
Emitter-Base Voltage	V <sub>EBO</sub>	-7	V
Continuous Collector Current	Ic	-4	Α
Peak Pulse Current	I <sub>CM</sub>	-10	A

# The rmal Characteristics ( $@T_A = +25^{\circ}C$ , unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
	(Note 5)		1.07	W
Power Dissipation	(Note 6)	$P_{D}$	2.3	W
	(Note 7)		3.4	W
	(Note 5)		140	°C/W
Thermal Resistance, Junction to Ambient	(Note 6)	R <sub>OJA</sub>	65	°C/W
	(Note 7)		44	°C/W
Thermal Resistance, Junction to Leads (Note 8)	R <sub>ÐJL</sub>	6	°C/W	
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +175	°C	

# ESD Ratings (Note 9)

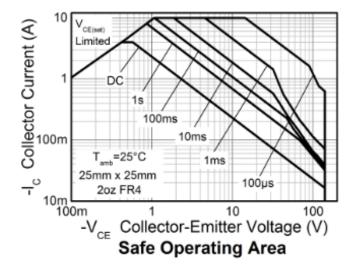
Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	С

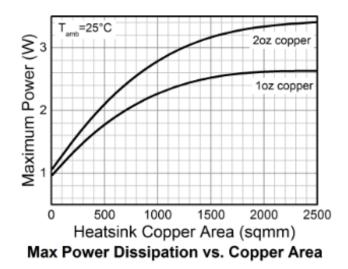
Notes:

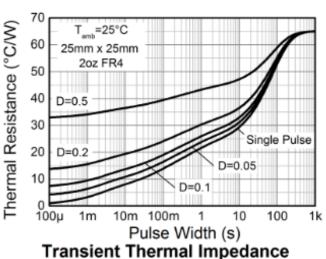
- 5. For a device mounted with the collector tab on MRP FR4-PCB; device is measured under still air conditions whilst operating in a steady-state.
- S. To a device friodined with the collector tab of MixT RAP-CB, device is meast
   Same as Note 5, except the device is mounted on 25mm × 25mm 2oz copper.
   Same as Note 5, except the device is mounted on 50mm × 50mm 2oz copper.
   Thermal resistance from junction to solder-point (at the collector tab).
   Refer to JEDEC specification JESD22-A114 and JESD22-A115.

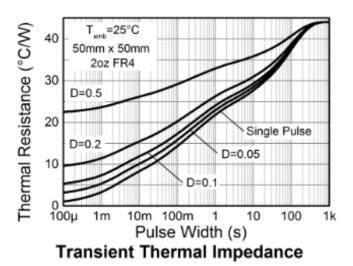


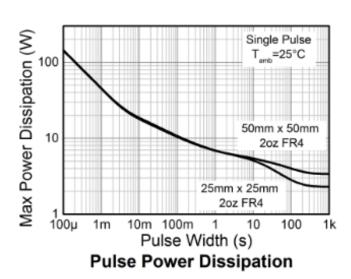
### **Thermal Characteristics and Derating Information**

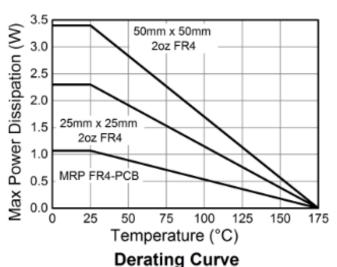














# **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

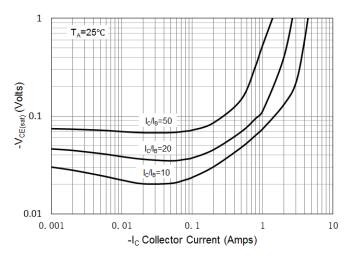
Characteristic	Symbol	Min	Тур.	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV <sub>CBO</sub>	-180	-216	_	V	I <sub>C</sub> = -100μA
Collector-Emitter Breakdown Voltage (Note 10)	BV <sub>CER</sub>	-180	_	_	V	$I_C = -1\mu A, R_B \le 1k\Omega$
Collector-Emitter Breakdown Voltage (Note 10)	BV <sub>CEO</sub>	-140	-164	_	V	I <sub>C</sub> = -1mA
Emitter-Base Breakdown Voltage	BV <sub>EBO</sub>	-7	-8.3	_	V	I <sub>E</sub> = -100μA
Collector Cut-Off Current		_	-1	-20	nA	V <sub>CB</sub> = -150V
Collector Cut-Off Current	I <sub>CBO</sub>	_	-0.1	-10	μA	V <sub>CB</sub> = -150V, T <sub>A</sub> = +125°C
Collector Cut-Off Current	I <sub>CER</sub>	_	-2	-20	nA	V <sub>CB</sub> = -150V
Collector Cut-Off Current	R≤1kΩ	_	-0.3	-10	μA	V <sub>CB</sub> = -150V, T <sub>A</sub> = +125°C
Emitter Cut-Off Current	I <sub>EBO</sub>	_	-1	-10	nA	V <sub>EB</sub> = -6V
		100	165	_	_	$I_C = -10 \text{mA}, V_{CE} = -5 \text{V}$
DC Current Transfer Static Ratio (Note 10)		100	154	300	_	I <sub>C</sub> = -1A, V <sub>CE</sub> = -5V
DC Current Transfer Static Ratio (Note 10)	h <sub>FE</sub>	45	65	_	_	$I_C = -3A$ , $V_{CE} = -5V$
		_	5	_	_	I <sub>C</sub> = -10A, V <sub>CE</sub> = -5V
	V <sub>CE(sat)</sub>	_	-37	-60	mV	$I_C = -100 \text{mA}, I_B = -5 \text{mA}$
Collector-Emitter Saturation Voltage (Note 10)		_	-47	-80	mV	$I_C = -0.5A$ , $I_B = -50mA$
Collector-Entitler Saturation Voltage (Note 10)		_	-72	-120	mV	I <sub>C</sub> = -1A, I <sub>B</sub> = -100mA
		_	-200	-360	mV	$I_C = -3A$ , $I_B = -300mA$
Base-Emitter Saturation Voltage (Note 10)	V <sub>BE(sat)</sub>	_	-918	-1040	mV	I <sub>C</sub> = -3A, I <sub>B</sub> = -300mA
Base-Emitter Turn-On Voltage (Note 10)	V <sub>BE(on)</sub>	_	-802	-930	mV	I <sub>C</sub> = -3A, V <sub>CE</sub> = -5V
Transitional Frequency	f <sub>T</sub>	_	120	_	MHz	I <sub>C</sub> = -100mA, V <sub>CE</sub> = -10V, f = 50MHz
Output Capacitance	C <sub>obo</sub>	_	33	_	pF	V <sub>CB</sub> = -10V, f = 1MHz
	t <sub>delay</sub>	_	9.7	_	ns	
Cuitabina Charastariatia	t <sub>rise</sub>	_	200	_	ns	V <sub>CC</sub> = -50V, I <sub>C</sub> = -1A,
Switching Characteristics	t <sub>storage</sub>	1	1500	_	ns	$I_{B1} = -I_{B2} = -100 \text{mA}$
	t <sub>fall</sub>	_	137	_	ns	

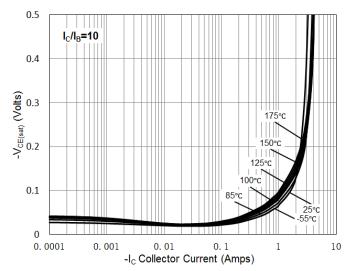
Note:

10. Measured under pulsed conditions. Pulse width  $\leq$  300 $\mu$ s. Duty cycle  $\leq$  2%.



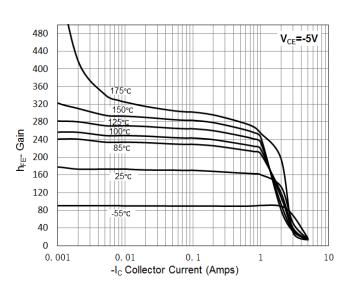
# Typical Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

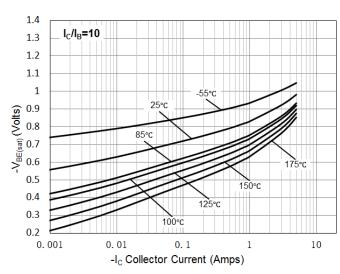




 $V_{\text{CE(sat)}}vs I_{\text{C}}$ 

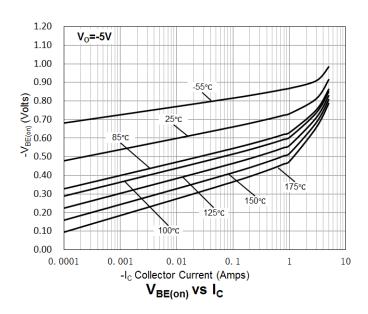
V<sub>CE(sat)</sub>vs I<sub>C</sub>





h<sub>FE</sub> vs I<sub>C</sub>

V<sub>BE(sat)</sub> vs I<sub>C</sub>

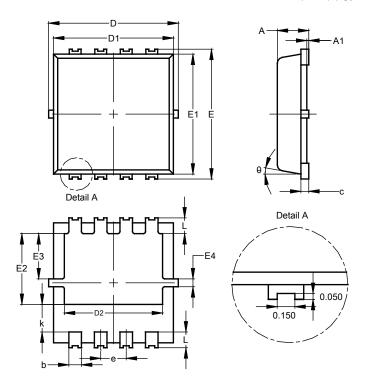




# **Package Outline Dimensions**

Please see https://www.diodes.com/package-outlines.html for the latest version.

### PowerDI3333-8 (SWP) (Type UX)

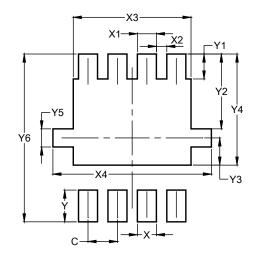


PowerDI3333-8 (SWP)						
	(Type UX)					
Dim	Min	Max	Тур			
Α	0.75	0.85	0.80			
A1	0.00	0.05				
b	0.25	0.40	0.32			
С	0.10	0.25	0.15			
D	3.20	3.40	3.30			
D1	2.95	3.15	3.05			
D2	2.30	2.70	2.50			
E	3.20	3.40	3.30			
E1	2.95	3.15	3.05			
E2	1.60	2.00	1.80			
E3	0.95	1.35	1.15			
E4	0.10	0.30	0.20			
е	_	_	0.65			
k	0.50	0.90	0.70			
L	0.30	0.50	0.40			
θ	0°	12°	10°			
All Dimensions in mm						

# **Suggested Pad Layout**

Please see https://www.diodes.com/package-outlines.html for the latest version.

### PowerDI3333-8 (SWP) (Type UX)



Dimensions	Value (in mm)		
С	0.650		
Х	0.420		
X1	0.420		
X2	0.230		
Х3	2.600		
X4	3.500		
Υ	0.700		
Y1	0.550		
Y2	1.650		
Y3	0.600		
Y4	2.450		
Y5	0.400		
Y6	3.700		

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device terminals and PCB tracking.



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